



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	23-08-2023
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H7S3L8H6H	22IB*485XXXY	A	9991	23-08-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	338.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	NAC	Copper Alloy	SACN305	

Package Designator	Size	Nbr of instances	Shape	
BGA	13x13	225	bulk solder	
Comment	Package : B04V TFBGA 13X13X1.2 225L P 0.80 MM DM00384539			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	221B*485XXX				6000000.0	1000001.9
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	6.999	mg	supplier	die	Silicon (Si)	7440-21-3		6.527	mg	932562	19311
				supplier	metallization	Aluminium (Al)	7429-90-5		0.056	mg	8001	166
				supplier	metallization	Copper (Cu)	7440-50-8		0.175	mg	25004	518
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	143	3
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.029	mg	4143	86
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	714	15
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	143	3
Substrate (A307800)	M-011 Other inorganic materials	83.886	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.205	mg	29290	607
				supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Proprietary		5.033	mg	60000	14891
				supplier	BT-substrate	Glass cloth	65997-17-3		22.058	mg	262950	65260
				supplier	BT-substrate	Copper foil	7440-50-8		27.557	mg	328500	81528
				supplier	Solder mask	Ethanol, 2-(2-ethoxyethoxy)-, 1-acetate	112-15-2		9.689	mg	115500	28665
				supplier	Solder mask	Naphtha (petroleum), heavy aromatic	64742-94-5		11.325	mg	135000	33505
				supplier	Solder mask	Methanone, (diphenylphosphinyl)(2,4,6-trimethyl-5-oxo-1,2,3,4-tetrahydro-1H-pyrimidin-2-ylidene)-	75980-60-8		2.810	mg	33500	8314
				supplier	Solder mask	TALC (CONTAINING NO ASBESTOS FIBRES)	14807-96-6		3.062	mg	36500	9059
				supplier	Solder mask	Dipropylene glycol Methylene Ether Acetate	88917-22-0		2.223	mg	26500	6577
				supplier	Solder mask	1,3,5-Triazine-2,4,6-triamine	108-78-1		0.130	mg	1550	385
DAF (2100AC)	M-011 Other inorganic materials	3.772	mg	supplier	film	Copper (Cu)	7440-50-8		3.123	mg	827850	9239
				supplier	film	Silver (Ag)	7440-22-4		0.290	mg	76850	858
				supplier	film	2,2-dimethyl-1,3-propanediyl bismethacrylate	1985-51-9		0.139	mg	36900	412
				supplier	film	A mixture of: 4-allyl-2,6-bis (2,3-epoxypropyl)phenylmethacrylate	Proprietary		0.101	mg	26900	300
				supplier	film	2-[[[2,2-bis[[[(1-oxoallyl)oxy]methyl]butoxy]methyl]oxy]ethoxy]ethyl methacrylate	94108-97-1		0.098	mg	26000	290
				supplier	film	tert-butyl peroxyneodecanoate	26748-41-4		0.019	mg	5000	56
Bonding wire (Cu)	Precious metals	1.488	mg	supplier	Bonding wire	Hydroquinone	123-31-9		0.002	mg	500	6
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.005	mg	3500	15
				supplier	Bonding wire	Copper (Cu)	7440-50-8		1.437	mg	965500	4250
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.046	mg	31000	136
Encapsulation (KE-G1250AAS)	M-011 Other inorganic materials	198.083	mg	supplier	Molding Compound	Epoxy resin	Proprietary		7.923	mg	40000	23442
				supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		178.275	mg	900000	527440
				supplier	Molding Compound	Phenol resin	Proprietary		11.093	mg	56000	32818
Solder balls (SACN305)	M-011 Other inorganic materials	43.772	mg	supplier	Molding Compound	Carbon Black	1333-86-4		0.792	mg	4000	2344
				supplier	Matte Sn	Tin (Sn)	7440-31-5		42.218	mg	964500	124906
				supplier	Matte Sn	Silver (Ag)	7440-22-4		1.313	mg	30000	3885
				supplier	Matte Sn	Copper (Cu)	7440-50-8		0.219	mg	5000	648
supplier	Matte Sn	Nickel (Ni)	7440-02-0		0.022	mg	500	65				